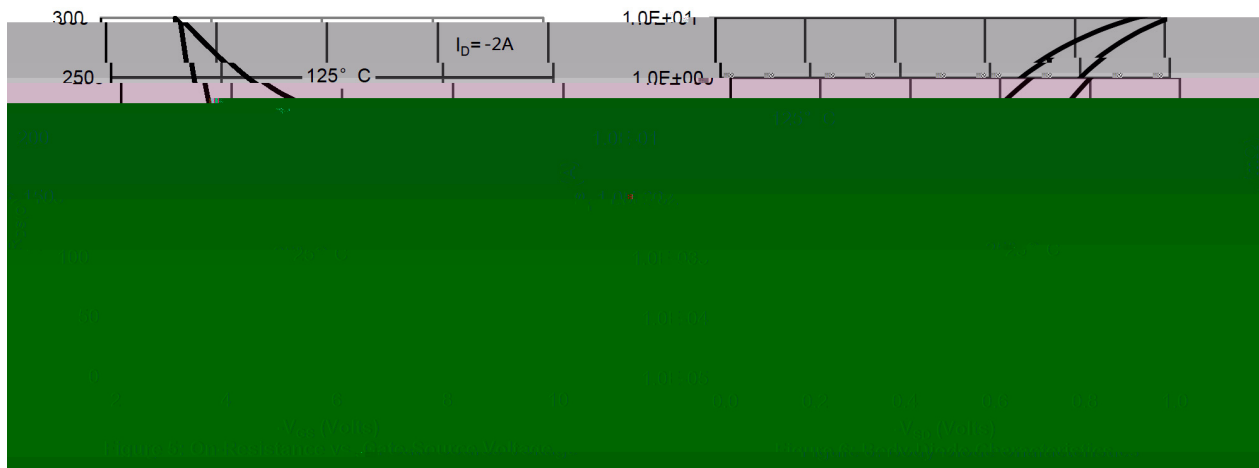
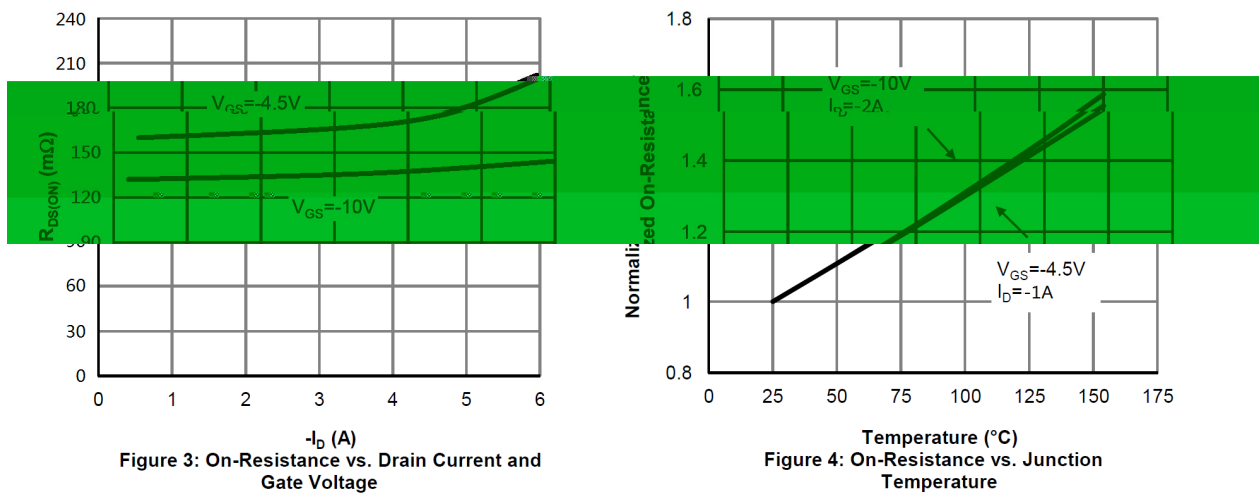
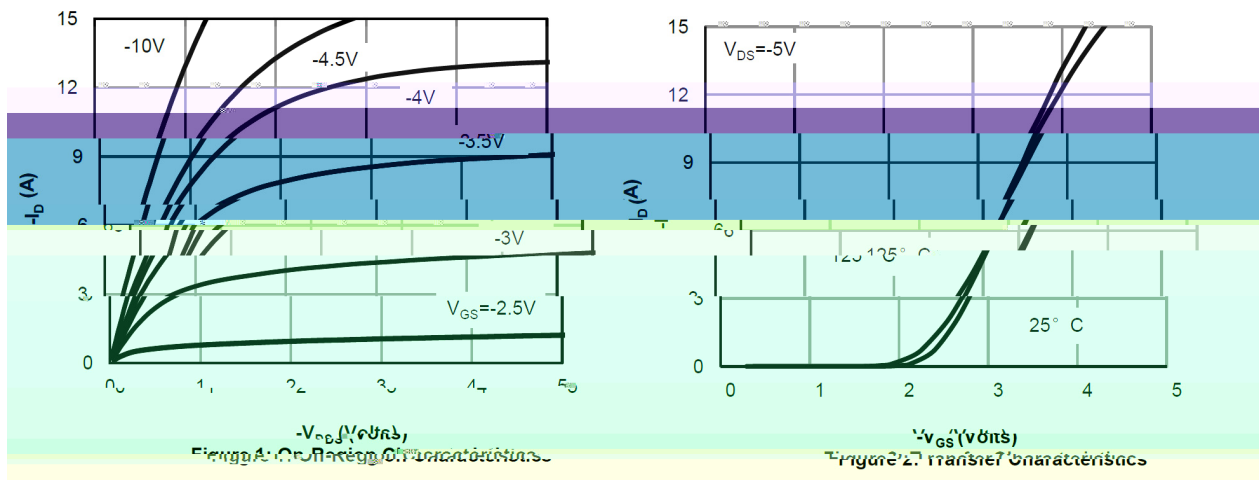


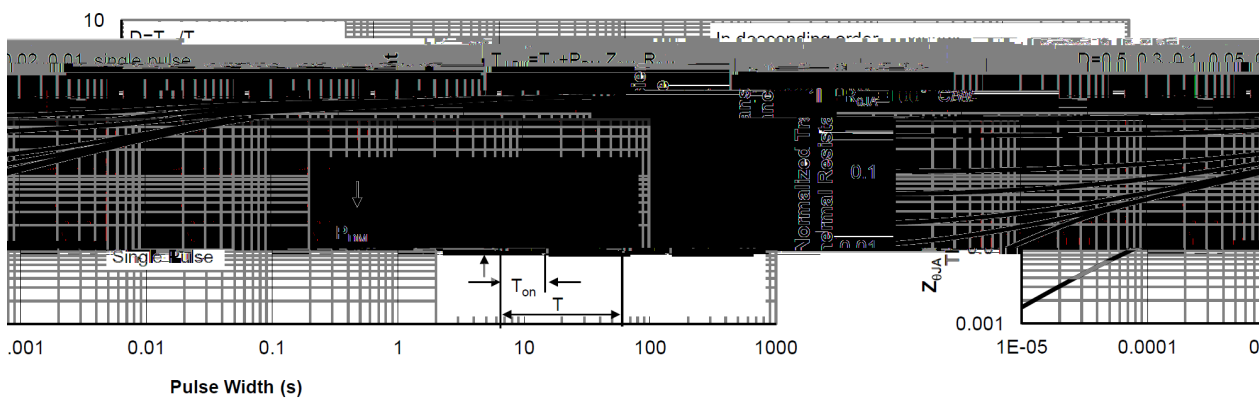
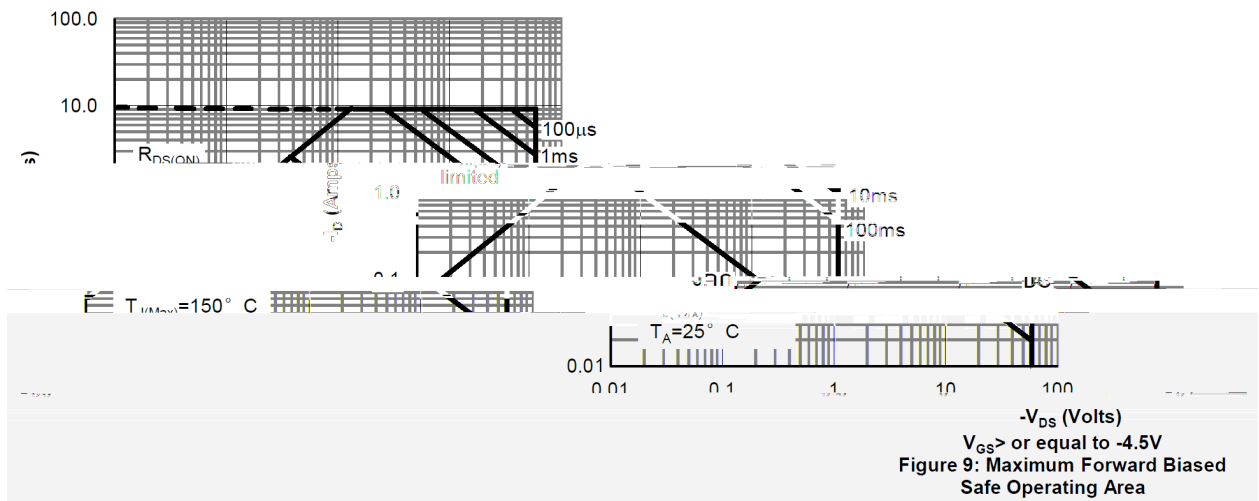
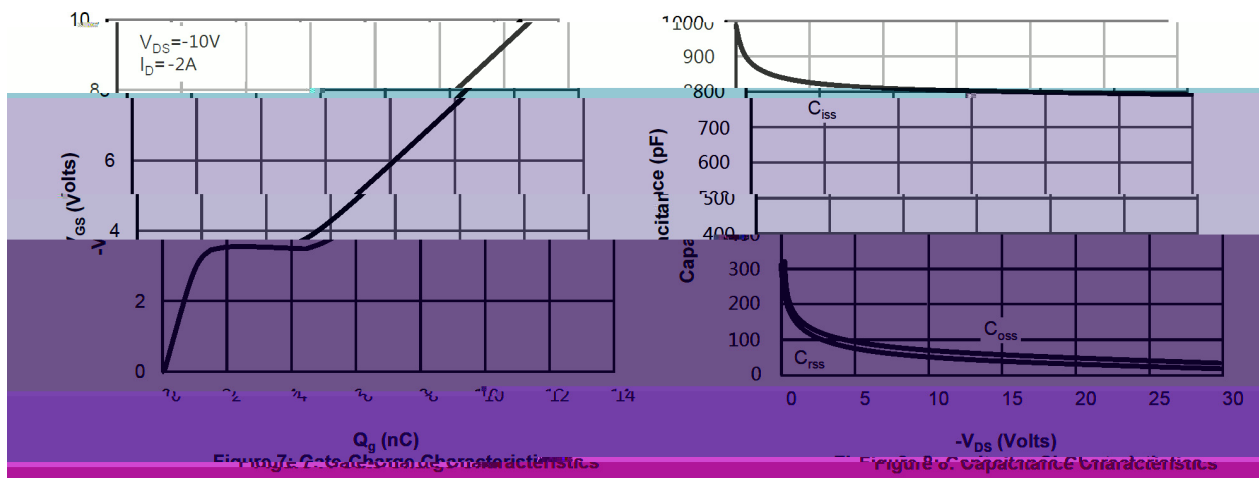
Rev.A Oct.-2022

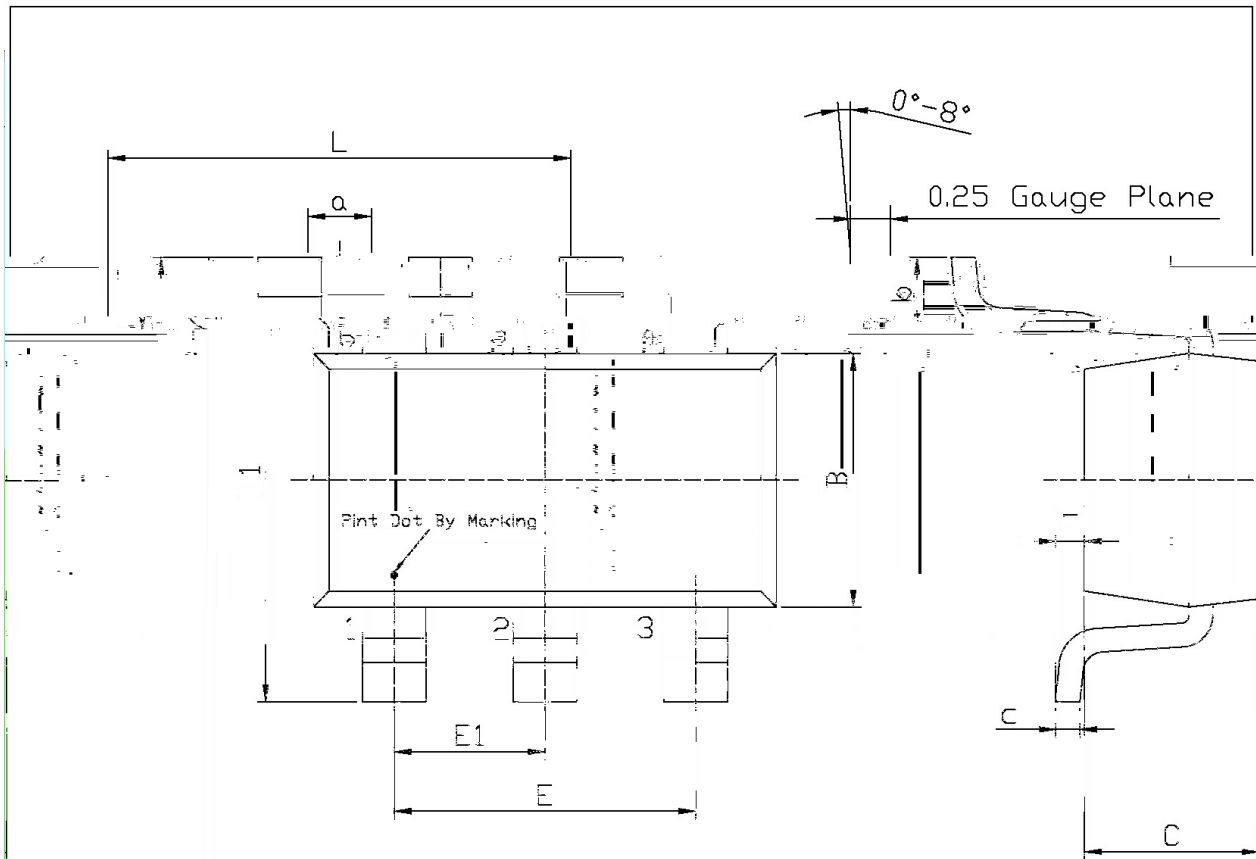
Parameter		Symbol	Rating	Unit
Drain–Source Voltage		V_{DS}	-60	V
Gate–Body Leakage Voltage		V_{GSS}	± 20	V
Drain Current – Continuous		I_D	-2.3	A
Pulsed Drain Current		I_{DM}	-9	A
Power Dissipation		P_D	1.25	W
Operating and Storage Temperature Range		T_J, T_{STG}	-55 150	
Maximum Junction-to-Ambient	$t \leq 10s$	$R_{\theta JA}$	72	/W
Maximum Junction-to-Ambient	Steady-State		100	/W
Maximum Junction-to-Lead	Steady-State	$R_{\theta JL}$	64	/W

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain–Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V$ $I_D=-250\mu A$	-60	-75		V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$ $I_D=-250\mu A$	-1	-1.9	-2.5	V
Static Drain–Source On–Resistance	$R_{DS(on)}$	$V_{GS}=-10V$ $I_D=-2A$		135	150	m Ω
		$V_{GS}=-4.5V$ $I_D=-1A$		160	200	m Ω
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=-60V$ $V_{GS}=0V$			-1.0	μA
Gate–Body leakage current	I_{GSS}	$V_{GS}=\pm 20V$ $V_{DS}=0V$			± 100	nA
Drain–Source Diode Forward Voltage	V_{SD}	$V_{GS}=0V$ $I_S=-1A$ $T_J=25$			-1.2	V
Gate resistance	R_g	$f=1MHz$		6.5		Ω
Input Capacitance	C_{iss}	$V_{DS}=-25V$ $V_{GS}=0V$ $f=1.0MHz$		800		pF
Output Capacitance	C_{oss}			45		
Reverse Transfer Capacitance	C_{rss}			35		
Total Gate Charge	$Q_{g(-10V)}$	$V_{DS}=-10V$ $V_{GS}=-10.0V$ $I_D=-2A$		12.3		nC
Total Gate Charge	$Q_{g(-4.5V)}$			6.3		
Gate-to-Source Charge	Q_{gs}			1.6		
Gate-to-Drain Charge	Q_{gd}			2.4		
Turn–On Delay Time	$t_{d(on)}$	$V_{DS}=-10V$ $R_L=5.4\Omega$ $V_{GS}=-10V$ $R_{GEN}=3\Omega$		12		ns
Turn–On Rise Time	t_r			20		
Turn–Off Delay Time	$t_{d(off)}$			20		
Turn–Off Fall Time	t_f			25		



Rev.A Oct.-2022

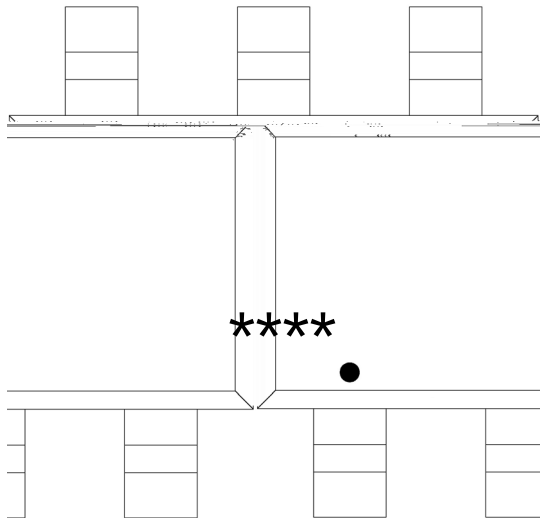




Unit: mm

Symbol	Dimensions In Millimeters		Symbol	Dimensions In Millimeters	
	Min	Max		Min	Max
L	2.82	3.32	E1	0.85	1.05
B	1.50	1.70	a	0.35	0.50
C	0.90	1.30	c	0.10	0.20
L1	2.60	3.00	b	0.35	0.55
E	1.80	2.00	F	0	0.15

SOT23-6

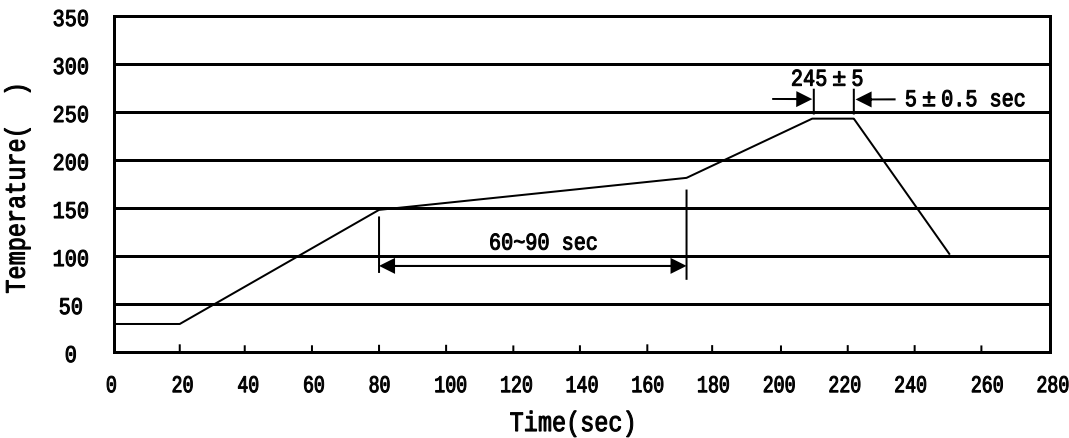


2P06:

Note:

2P06	Product Type
*****	Company Code

Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- 1

150 180

60 90sec;

1.Preheating:150~180 , Time:60~90sec.
- 2

245 5

5 0.5sec;

2.Peak Temp.:245 5 , Duration:5 0.5sec.
- 3

2 10 /sec.

3. Cooling Speed: 2~10 /sec.

260 5

10 1 sec.

Temp.:260 5

Time:10 1 sec

/ REEL

Package Type	Units					Dimension (unit mm ³)		
	Units/Reel	Reels/Inner Box	Units/Inner Box	Inner Boxes/Outer Box	Units/Outer Box	Reel	Inner Box	Outer Box
SOT23-5/6	3,000	10	30,000	4	120,000	7 ×8	210×205×205	445×230×435